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DWG NO.

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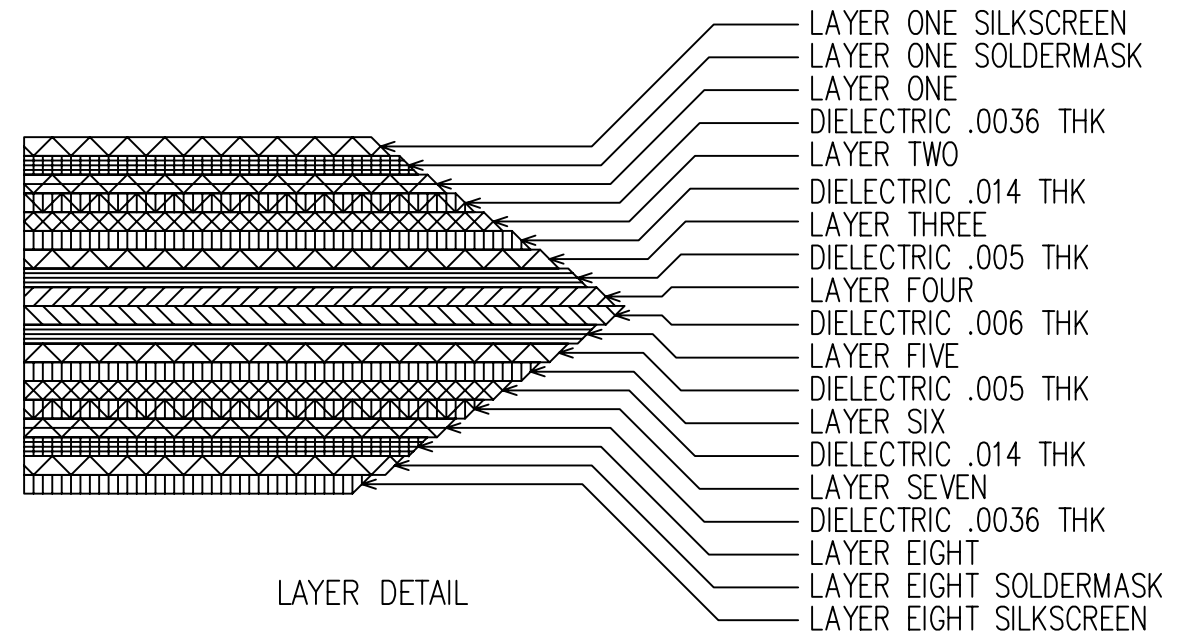
REVISIONS

ZONE	LTR	DESCRIPTION	DATE	APPROVED
	1.0	INITIAL RELEASE		
	2.5			
	3.1			
	4.1			
	5.0			

NOTES:

1. PRINTED CIRCUIT BOARD MUST MEET REQUIREMENTS OF IPC-6012, CLASS 2.
2. INSPECT PER IPC-A-600, CLASS 2.
3. MATERIAL: FR4 PER IPC-4101/24.  
1/2 OZ BASE COPPER ON EXTERNAL LAYERS.  
1 OZ BASE COPPER ON INTERNAL LAYERS.
4. BOARD THICKNESS: .062 +/- .007.
5. APPLY SOLDERMASK OVER BARE COPPER ON BOTH SIDES PER IPC-SM-840, TYPE B, CLASS 2 (COLOR GREEN).
6. APPLY SILKSCREEN ON BOTH SIDES USING WHITE EPOXY INK.
7. THE FRONT TO BACK REGISTRATION TO BE WITHIN +/- .005.
8. ALL HOLES ARE TO BE PLATED THRU UNLESS OTHERWISE SPECIFIED.
9. FINISH: 3-6 MICROINCHES IMMERSION GOLD OVER 120-225 MICROINCHES ON NICKEL.
10. CHARACTERISTIC IMPEDANCE OF LAYERS 1 AND 8 (.006" TRACES) TO BE 50 OHMS ± 10%.  
CHARACTERISTIC IMPEDANCE OF LAYERS 4 AND 5 (.0055" TRACES) TO BE 50 OHMS ± 10%.  
SHOWN DIELECTRIC THICKNESS IS FOR REFERENCE ONLY AND CAN BE ADJUSTED TO ACHIEVE REQUIRED CONTROLLED IMPEDANCE.
11. IF APPLICABLE, IN THE INSTANCE OF A SURFACE MOUNT PAD BURIED IN THE COPPER, SOLDERMASK OPENING OF THOSE PADS MUST BE "PAD DEFINED".

△ NO COPPER ALLOWED IN THIS AREA.



LAYER DETAIL

QTY REQD	-001	CAGE CODE	PART OR IDENTIFYING NO.	NOMENCLATURE OR DESCRIPTION	MATERIAL SPECIFICATION	ITEM NO.
PARTS LIST						
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES: TOLERANCES ON:				DRAWN	ACDI/MKW 2/26/10	
FRACTIONS DECIMALS ANGLES				CHECKED	AK MISHRA	
± .XX ± .01 ±				ELECT ENGRG		
.XXX ± .005				MECH ENGRG		
SURFACE ROUGHNESS				QA		
CONTRACT NO.				MANUF		
NEXT ASSY				PROGRAM		
USED ON				SIZE	CAGE CODE	DWG NO.
APPLICATION				D		
				SCALE: NONE	REV 5.0	
				SHEET 1 OF 3		

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